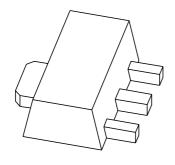
### **DISCRETE SEMICONDUCTORS**

## DATA SHEET



**PBSS5250X** 50 V, 2 A PNP low  $V_{CEsat}$  (BISS) transistor

Objective specification

2003 Jun 17





## 50 V, 2 A PNP low V<sub>CEsat</sub> (BISS) transistor

### **PBSS5250X**

#### **FEATURES**

- SOT89 (SC-62) package
- Low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability: I<sub>C</sub> and I<sub>CM</sub>
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements.

#### **APPLICATIONS**

- · Power management
  - DC/DC converters
  - Supply line switching
  - Battery charger
  - LCD backlighting.
- · Peripheral drivers
  - Driver in low supply voltage applications (e.g. lamps and LEDs).
  - Inductive load driver (e.g. relays, buzzers and motors).

#### **DESCRIPTION**

NPN low  $V_{\text{CEsat}}$  transistor in a SOT89 plastic package. NPN complement: PBSS4250X.

#### MARKING

TYPE NUMBER	MARKING CODE(1)		
PBSS5250X	*1L		

#### Note

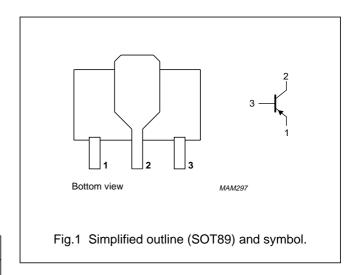
1. \* = p : made in Hong Kong\* = t : made in Malaysia\* = W : made in China.

#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	-50	V
I <sub>C</sub>	collector current (DC)	-2	Α
I <sub>CM</sub>	peak collector current	<b>-</b> 5	Α
R <sub>CEsat</sub>	equivalent on-resistance	160	mΩ

#### **PINNING**

PIN	DESCRIPTION		
1	emitter		
2	collector		
3	base		



## 50 V, 2 A PNP low V<sub>CEsat</sub> (BISS) transistor

PBSS5250X

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-50	V
$V_{CEO}$	collector-emitter voltage	open base	_	-50	V
$V_{EBO}$	emitter-base voltage	open collector	_	<b>-</b> 5	V
I <sub>C</sub>	continuous collector current (DC)		_	-2	Α
I <sub>CM</sub>	peak collector current	T <sub>j max</sub>	_	<b>-</b> 5	А
I <sub>B</sub>	continuous base current (DC)		_	-0.5	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
		note 1	_	550	mW
		note 2	_	1	W
T <sub>j</sub>	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

#### **Notes**

- 1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.
- 2. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air		
		note 1	225	K/W
		note 2	125	K/W
R <sub>th-js</sub>	thermal resistance from junction to soldering point		16	K/W

#### **Notes**

- 1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.
- 2. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

# 50 V, 2 A PNP low $V_{CEsat}$ (BISS) transistor

PBSS5250X

#### **CHARACTERISTICS**

 $T_j = 25$  °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	$V_{CB} = -50 \text{ V}; I_{E} = 0$		-100	nA
		$V_{CB} = -50 \text{ V}; I_E = 0; T_j = 150 ^{\circ}\text{C}$	_	-50	μΑ
I <sub>CES</sub>	collector cut-off current	$V_{CE} = -50 \text{ V}; V_{BE} = 0$	_	-100	nA
I <sub>EBO</sub>	emitter cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0$	_	-100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = −2 V			
		$I_{\rm C} = -0.1  {\rm A}$	200	_	
		$I_{C} = -0.5 \text{ A}$	200	_	
		$I_{C} = -1 \text{ A}$ ; note 1	200	_	
		$I_{C} = -2 \text{ A}$ ; note 1	100	_	
V <sub>CEsat</sub>	collector-emitter saturation	$I_C = -0.5 \text{ A}; I_B = -50 \text{ mA}$	_	-90	mV
	voltage	$I_C = -1 \text{ A}; I_B = -50 \text{ mA}$	_	-250	mV
		$I_C = -2 \text{ A}; I_B = -100 \text{ mA}$	_	-380	mV
		$I_C = -2 \text{ A}; I_B = -200 \text{ mA}; \text{ note 1}$	_	-320	mV
R <sub>CEsat</sub>	equivalent on-resistance	$I_C = -2 \text{ A}$ ; $I_B = -200 \text{ mA}$ ; note 1	_	160	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage	ge $I_C = -2 \text{ A}; I_B = -100 \text{ mA}$		-1.1	V
V <sub>BEon</sub>	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V; } I_{C} = -1 \text{ A}$	-1.1	_	V
f <sub>T</sub>	transition frequency	$I_C = -100 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz	100	_	MHz
C <sub>c</sub>	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	_	35	pF

#### Note

1. Pulse test:  $t_p \le 300 \ \mu s; \ \delta \le 0.02.$ 

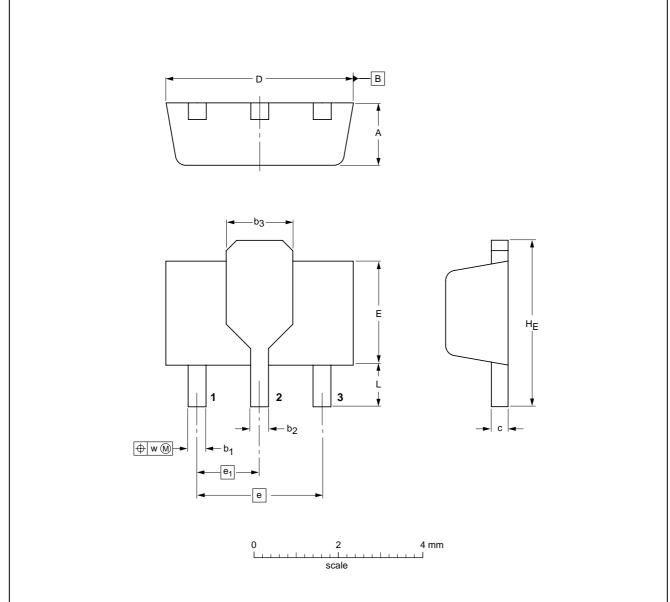
50 V, 2 A PNP low  $V_{CEsat}$  (BISS) transistor

PBSS5250X

#### **PACKAGE OUTLINE**

Plastic surface mounted package; collector pad for good heat transfer; 3 leads

**SOT89** 



#### DIMENSIONS (mm are the original dimensions)

UNIT	Α	b <sub>1</sub>	b <sub>2</sub>	b <sub>3</sub>	С	D	E	e	e <sub>1</sub>	HE	L min.	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.37	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	0.8	0.13

OUTLINE	TLINE REFERENCES					ISSUE DATE	
VERSION IEC		JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT89		TO-243	SC-62			<del>97-02-28</del> 99-09-13	

### 50 V, 2 A PNP low V<sub>CEsat</sub> (BISS) transistor

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#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

#### **DEFINITIONS**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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PBSS5250X

NOTES

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